#### Addition of Alternate Assembly Site ASE Korea for Select LFCSP Products

# **Qualification Results Summary for AD7689 in Sawn LFCSP at AEK**

TEST	SPECIFICATION	SAMPLE SIZE	RESULT	
Temperature Cycle (TC)*	JEDEC JESD22-A104	3 x 77	PASS	
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	PASS	
Highly Accelerated Stress Test (HAST)*	JEDEC JESD22-A110	3 x 77	PASS	
High Temperature Storage (HTS)	JEDEC JESD22-A103	1 x 77	PASS	
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC JESD22-A118	3 x 77	PASS	
Electrostatic Discharge Field-Induced Charge Device Model	JEDEC JS-002	3/voltage	PASS ±1250V	

<sup>\*</sup> Preconditioned per JEDEC/IPC J-STD-020.

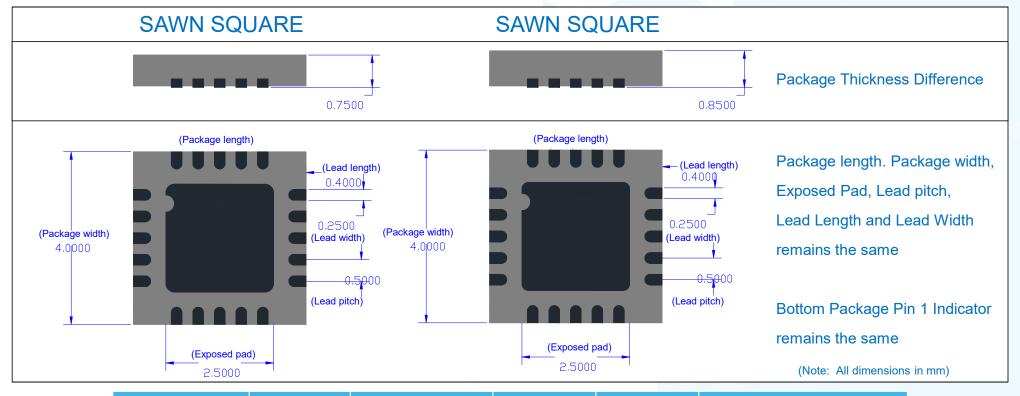
## Bill of Materials Change Description



MATERIALS	FROM	то	REMARKS		
Die Attach	Ablestik 8290	Ablestik 8290	Same		
Wire type	Gold Wire	Gold Wire	Same		
Mold Compound	Sumitomo G700	Sumitomo G700	Same		
Lead Finish	Matte Sn	Matte Sn	Same		

#### Package Outline Drawing





Body Size (mm)	Lead Count	ead Count Lead Pitch (mm)		0.85mm Sawn POD	Exposed Pad Size (mm)	
4x4	20	0.50	CP-20-10	CP-20-22	2.50	

## Package Outline Drawing (Dimensional Analysis)



Body Size (mm)	Lead Count	Sawn Type 0.75mm LFCSP				Sawn Type 0.85mm LFCSP			
		POD Spec	E-pad Size (mm sq.)	Lead Length (mm)	Lead Width (mm)	POD Spec	E-pad Size (mm sq.)	Lead Length (mm)	Lead Width (mm)
4x4	20	CP-20-10	2.50 (+/- 0.15)	0.40 (+/- 0.10)	0.25 (+/- 0.05)	CP-20-22	2.50 (+/- 0.15)	0.40 (+/- 0.10)	0.25 (+/- 0.05)